



SOT146-1

plastic dual in-line package; 20 leads (300 mil)

21 April 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	DIP20
Package type industry code	DIP20
Package style descriptive code	DIP (dual in-line package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MS-001
JEITA package outline code	SC-603
Mounting method type	T (through-hole mount)
Issue date	13-2-2003

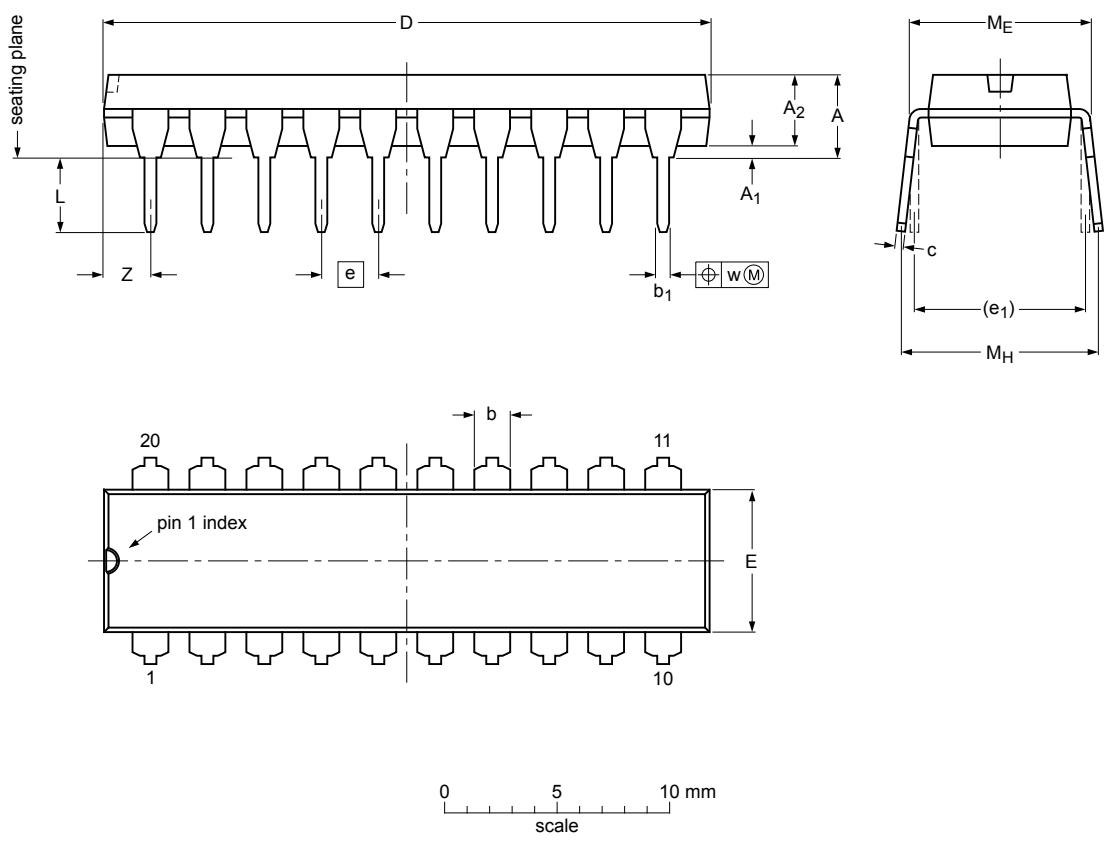
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	26.03	-	-	26.29	mm
E	package width	6.22	-	6.35	6.4	mm
A	seated height	-	-	4.2	4.2	mm
A ₂	package height	-	-	3.04	3.2	mm
e	nominal pitch	-	-	-	-	
n ₂	actual quantity of termination	-	-	20	-	



2. Package outline

DIP20: plastic dual in-line package; 20 leads (300 mil) SOT146-1



Dimensions (mm are the original dimensions)

Unit ⁽¹⁾	A	A ₁	A ₂	b	b ₁	c	D ⁽¹⁾	E ⁽¹⁾	e	e ₁	L	M _E	M _H	w	Z ⁽¹⁾
max	4.2		3.2	1.73	0.53	0.36	26.29	6.40			3.60	8.25	10.0		2
mm nom									2.54	7.62				0.254	
min		0.51		1.30	0.38	0.23	26.03	6.22			3.05	7.80	8.3		

Note

1. Plastic or metal protrusions of 0.25 mm (0.01 inch) maximum per side are not included.

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Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT146-1		MS-001	SC-603		-03-02-13- 15-12-10

Fig. 1. Package outline DIP20 (SOT146-1)

3. Legal information

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4. Contents

1. Package summary.....	1
2. Package outline.....	2
3. Legal information.....	3

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